

**Amendments to the Specification**

**Please replace paragraph [0017] with the following amended paragraph:**

[0017] An advantage of the present invention is to provide a method of manufacturing an LCD device in which liquid crystal is uniformly distributed by a liquid crystal dispensing method ~~under a structure having a dielectric frame.~~

**Please replace paragraph [0021] with the following amended paragraph:**

[0021] In the preferred embodiment of the present invention, the dielectric frame is formed to drive liquid crystal molecules in various directions, and a step difference between the dielectric frame and the sealant is obtained so that the dielectric frame does not hinder the movement of the liquid crystal from being injected after the first and second substrates are bonded to each other. The liquid crystal is uniformly distributed in the panel. Also, if the liquid crystal is formed not injected by a vacuum injection method, but by a dispensing method which does not require a liquid crystal injection hole may be used, and the liquid crystal is uniformly distributed in the panel.

**Please replace paragraph [0040] with the following amended paragraph:**

[0040] FIG. 2A shows a TFT panel having gate lines 53 on a substrate 51, a gate insulating layer 55 on the gate lines 53 and the substrate [[53]]51, and a passivation layer 57. FIG. 2B shows the ITO layer 59 having a contact hole, for example

**Please replace paragraph [0041] with the following amended paragraph:**

[0041] Referring to FIGs. 6-8, an electric field inducing window may be formed in the pixel electrode 59 (60a), the passivation film 57 (60b) and/or the gate insulating film 55 (60c). The electric field inducing window may have a slit or hole substantially circular shape. For example, as shown in FIG. 6, the slit 60a is formed in the pixel electrode 59. FIG. 7 shows a

hole 60b formed in the passivation film 57. FIG. 8 shows a hole 60b formed in the passivation film 57 and the gate insulating film 55.

**Please replace paragraph [0050] with the following amended paragraph:**

[0050] Subsequently, as shown in FIG. 2D, an ultraviolet ray hardening sealant or a sealant 69 that can be hardened by heat and ultraviolet ray irradiation is formed in a sealing region on the second substrate 51a. The sealant is formed to have a height greater than that of the dielectric frame. The liquid crystal layer 100 is formed on the first substrate 51 by a dispensing method. The sealant may be a double sealant formed in a double structure. After the liquid crystal layer is formed, the first and second substrates are attached to each other, as shown in FIG. 2E.

**Please replace paragraph [0053] with the following amended paragraph:**

[0053] The height of the sealant is higher than the height of the dielectric frame. Preferably, the difference in the height is more than  $1\mu$ . If the height of the sealant becomes lower, the height of the dielectric frame becomes lower. The height of the sealant may be proportional to the height of the dielectric frame. The dielectric frame should have a minimum height to efficiently provide electric field distortion. Table I shows a mutual relationship between the height of the sealant and the height of the dielectric frame to facilitate movement of the liquid crystal in the liquid crystal layer.